

产品规格书

SPECIFICATIONS FOR PRODUCT

产品类型 TYPE: Crystal Oscillator

产品规格 SPEC : 33.33MHz/3225/3.3V

产品型号 P/N : CJO05-333303320B30

日期 DATE: 2021/05/06

核准及签名			番り、コ
R&D APPR. SIGNATURED			DEPT.
拟制	审核	批准	频率器件事业部
ISSUE	CHECK	APPROVAL	
Ivan	Abbey	Ken	
2021/05/06	2021/05/06	2021/05/06	

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JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

SMD3.2 * 2.5 Crystal Oscillator

CJO05-333303320B30

 Scope

- 1.1 This specification applies to the RoHS crystal oscillator with a frequency of 33.33MHz which will be used in electronic equipment.
- 2. Construction:
- 2.1 Oscillators series: SMD 3.2×2.5 XO
- 2.2 Package: SMD 3.2×2.5
- 3. Electrical Characteristics

3.1 Nominal Frequency: 33.33MHz3.2 Frequency Stability: ±20ppm

(incl. 25°C tolerance)

3.3 Aging: ±3ppm/year

3.4 Operating Temperature Range: -40° C to $+85^{\circ}$ C

3.5 Storage Temperature Range: -55° C to $+125^{\circ}$ C

3.6 Input Voltage (V_{DD}): +3.3 Vdc±10%

3.7 Input Current (I_{DD}): 10mA max

3.8 Output Waveform: CMOS

3.9 Output Symmetry: 50±10%

3.10 Rise/Fall Time: 8ns max

3.11 Output Voltage V_{OL}: 10%VDD

 V_{OH} : 90%VDD

3.12 Output Load: 15pF

3.13 Output State Control: Enable/disable

3.14 Start-up Time: 5ms max3.15 Standby current: 10μA max

3.16 Period Jitter: 40ps max (PK-PK)

3.17 Phase Jitter(RMS): 1ps max (12KHz to 20MHz)

3.18 Oscillation mode: A1

3.19 Others: Not recommended for safety applications

4. Reliability Specifications

This is the quality control and quality assurance and relaibility tests performance data for the RoHS 33.33MHz SMD 3.2×2.5 XO

related to the specification and approval sheet provided by JSCJ.

Standard test condition (TEMP.: 20±15℃. Relative humidity: 65±20%)

For any discripancy in GO/NG, test will be done at TEMP.25±2℃. R.H. 65±5%.

NO.	ITEM	SPECIFICATION	TEST METHOD
4.1	Temperature Cycle (GB/T 2423.22-2002, Method Nb)	Frequency change after test≤± 5ppm.	10 cycles from -55°C to 125°C. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.2	Low Temperature Storage (GB/T 2423.1-2001, Method Aa)	Frequency change after test≤± 5ppm.	Spending 72 hrs at -55°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.3	High Temperature Storage (GB/T 2423.2-2001, Method Ba)	Frequency change after test≤± 5ppm.	Spending 72 hrs at 125°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.4	Humidity (GB/T 2423.3- 2006, Method Cab)	Frequency change after test≤± 5ppm.	Spending 96 hrs at 40 °C ± 3 °C, with 90± 3% R.H. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.5	Vibration (GB/T 2423.10- 1995, Method Fc)	Frequency change after test≤± 5ppm.	Apply 0.75mm vibration at sweep frequency $10\sim500$ Hz, for 2h. 10 cycles in each direction of 3 axis. Measurement taken after 1 hour.
4.6	Shock (GB/T 2423.5-1995, Method Ea)	Frequency change after test≤± 5ppm. No visible damages.	Peak 1000m/s2, normal width 6ms half sine wave form, 3.7m/s, 3 perpendicular axis of samples, 3 cycles / direction, total 18 cycles. Measurement taken after 1 hour.
4.7	Drop (GB/T 2423.8-1995, Method Ed)	Frequency change after test≤± 5ppm. No visible damages.	Free drop to the wooden plate from 1.0 m heights for 3 times.
4.8	Solderability (GB/T 2423.28-2005, Method Tc)	Terminals shall be covered more then 95% with solder.	In 245 \pm 5°C solder bath for 2 \pm 0.5 seconds. There is no need to do functioned test. 8-12X magnifier.
4.9	Terminal Strength (JIS-C-6429 Method 1 & 2)	No visible damage	Mount on a glass-epoxy board (100x50x1.6mm), then bend to 2mm displacement (velocity 1mm/sec) and keep for 5 seconds. or pulling force 0.5 kg for at least 60 seconds.
4.10	Resistance to Soldering Heat (GB/T 2423.28-2005, Test Tb Method 1B)	Frequency change after test≤± 5ppm.	Passed through the re-flow oven under the following condition. Preheat to 150°C±5°C for 60 to 120sec,and peak 265°C±5°C for 10s±3sec.Measurement taken after DUT being left at room temperature for at 24±2 hours.
4.11	OTHERS		

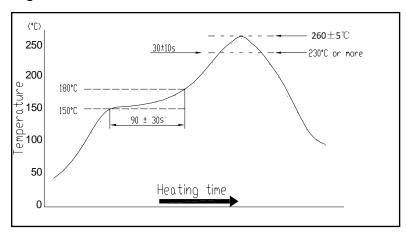
Recommended Reflow soldering condition

5. Recommended Reflow soldering condition (SMD)

Solder profile

Peak: 260±5℃ Soldering zone: 230℃ or more, 30±10s.

Pre-heating zone 1: 150~180°C, 90±30s

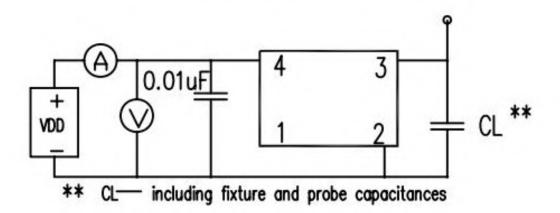


Temperature profile for reflow soldering

6. Soldering iron method

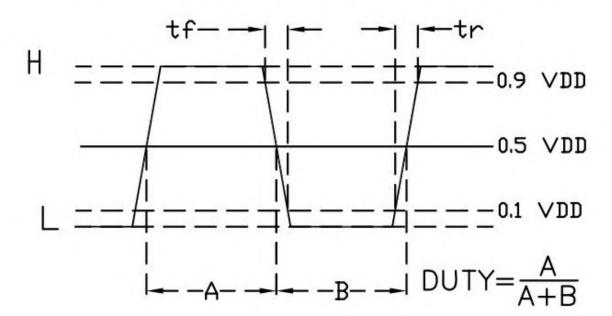
Bit temperature: $350\pm10^{\circ}$ C Application time of soldering iron:3+1 s For other procedures, refer to IEC 60068-2-20.

CMOS TEST CIRCUIT



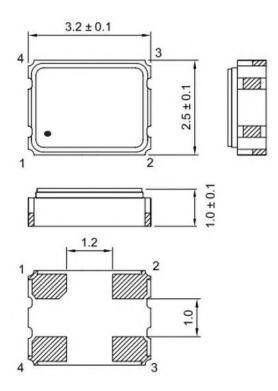
OUTPUT WAVEFORM (CMOS LOAD)

TYPICAL CMOS WAVE FORM



Package Outline Dimensions

Units:mm

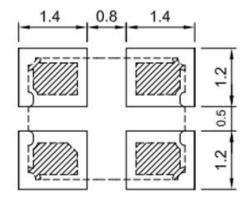


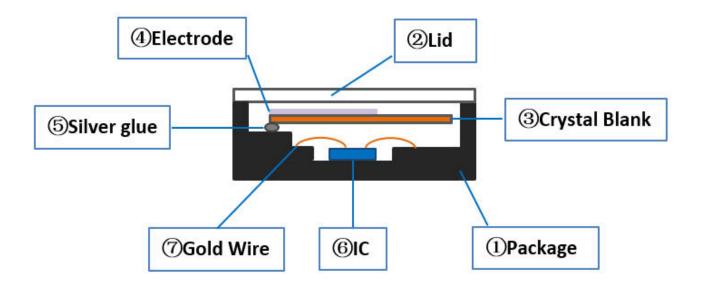
PIN CONNECTION

P/N	CJO05	
1	Enable/Disable*	
2	GND	
3	Output	
4	VDD	

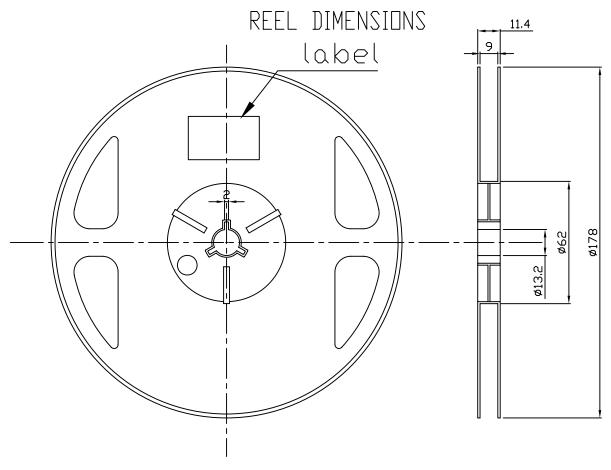
Enable/Disable functional description
When pin1 goes high (>=0.7VDD) or open the Oscillator in
normal operation and has output in frequency. When pin1
goes low (<=0.3VDD) the oscillator stops and the oscillator
output (Pin3) becomes high impedance.

Suggested Pad Layout

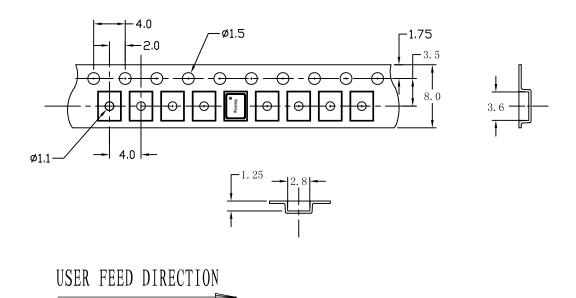




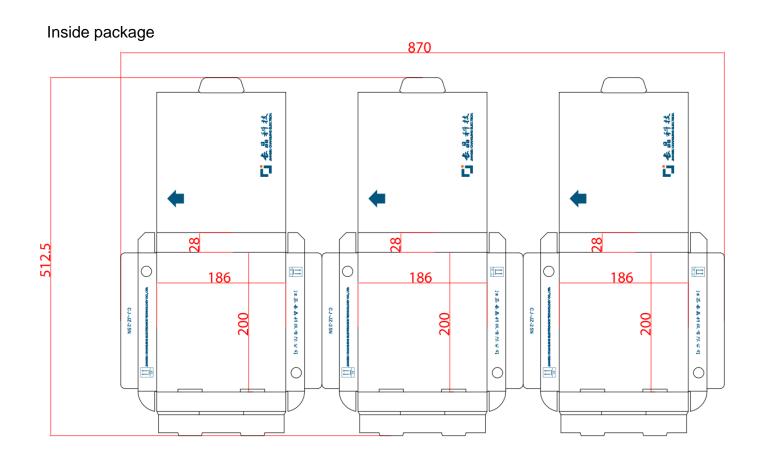
No.	Components	Materials
1	Package	Ceramic(Al ₂ O ₃)
2	Lid	KV(Fe/Ni/Co)
3	Crystal blank	SiO ₂
4	Electrode	Ag、Cr
5	Silver glue	Ag、CH₃OH、SiO₂
6	IC	Si
7	Gold Wire	Au



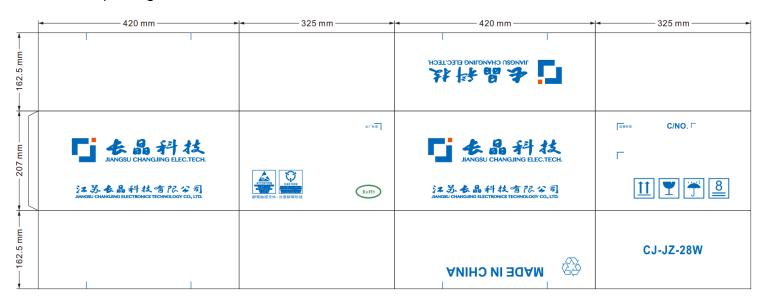
EMBOSSED TYPE DIMENSIONS



Package



Outside package



NOTICE

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